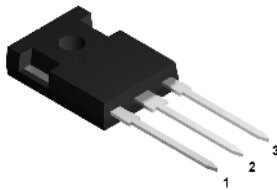
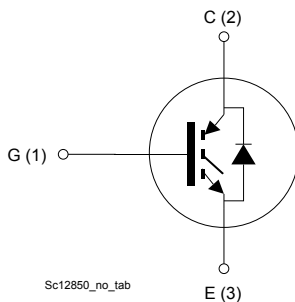


## Trench gate field-stop 650 V, 50 A low-loss M series IGBT in a TO-247 long leads package



TO-247 long leads



### Features

- Maximum junction temperature:  $T_J = 175\text{ °C}$
- 6  $\mu\text{s}$  of minimum short-circuit withstand time
- $V_{CE(sat)} = 1.65\text{ V (typ.) @ } I_C = 50\text{ A}$
- Tight parameter distribution
- Safer paralleling
- Positive  $V_{CE(sat)}$  temperature coefficient
- Low thermal resistance
- Soft- and fast-recovery antiparallel diode

### Applications

- Motor control
- UPS
- PFC
- General purpose inverter

### Description

This device is an IGBT developed using an advanced proprietary trench gate field-stop structure. The device is part of the M series IGBTs, which represent an optimal balance between inverter system performance and efficiency where the low-loss and the short-circuit functionality is essential. Furthermore, the positive  $V_{CE(sat)}$  temperature coefficient and the tight parameter distribution result in safer paralleling operation.

#### Product status link

[STGWA50M65DF2](#)

#### Product summary

<b>Order code</b>	STGWA50M65DF2
<b>Marking</b>	G50M65DF2
<b>Package</b>	TO-247 long leads
<b>Packing</b>	Tube

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-emitter voltage ( $V_{GE} = 0\text{ V}$ )	650	V
$I_C^{(1)}$	Continuous collector current at $T_C = 25\text{ °C}$	80	A
	Continuous collector current at $T_C = 100\text{ °C}$	50	
$I_{CP}^{(2)}$	Pulsed collector current	150	A
$V_{GE}$	Gate-emitter voltage	$\pm 20$	V
$I_F^{(1)}$	Continuous forward current at $T_C = 25\text{ °C}$	80	A
	Continuous forward current at $T_C = 100\text{ °C}$	50	
$I_{FP}^{(2)}$	Pulsed forward current	150	A
$P_{TOT}$	Total power dissipation at $T_C = 25\text{ °C}$	375	W
$T_{STG}$	Storage temperature range	-55 to 150	$^{\circ}\text{C}$
$T_J$	Operating junction temperature range	-55 to 175	$^{\circ}\text{C}$

1. Limited by package.
2. Pulse width is limited by maximum junction temperature.

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thJC}$	Thermal resistance, junction-to-case, IGBT	0.4	$^{\circ}\text{C/W}$
	Thermal resistance, junction-to-case, diode	0.96	
$R_{thJA}$	Thermal resistance, junction-to-ambient	50	$^{\circ}\text{C/W}$

## 2 Electrical characteristics

$T_J = 25\text{ °C}$  unless otherwise specified.

**Table 3. Static characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage	$V_{GE} = 0\text{ V}, I_C = 250\text{ }\mu\text{A}$	650			V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}, I_C = 50\text{ A}$		1.65	2.1	V
		$V_{GE} = 15\text{ V}, I_C = 50\text{ A}, T_J = 125\text{ °C}$		1.95		
		$V_{GE} = 15\text{ V}, I_C = 50\text{ A}, T_J = 175\text{ °C}$		2.1		
$V_F$	Forward on-voltage	$I_F = 50\text{ A}$		1.85	2.65	V
		$I_F = 50\text{ A}, T_J = 125\text{ °C}$		1.65		
		$I_F = 50\text{ A}, T_J = 175\text{ °C}$		1.55		
$V_{GE(th)}$	Gate threshold voltage	$V_{CE} = V_{GE}, I_C = 1\text{ mA}$	5	6	7	V
$I_{CES}$	Collector cut-off current	$V_{GE} = 0\text{ V}, V_{CE} = 650\text{ V}$			25	$\mu\text{A}$
$I_{GES}$	Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = \pm 20\text{ V}$			$\pm 250$	nA

**Table 4. Dynamic characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{ies}$	Input capacitance	$V_{CE} = 25\text{ V}, f = 1\text{ MHz}, V_{GE} = 0\text{ V}$	-	4200	-	pF
$C_{oes}$	Output capacitance		-	252	-	nF
$C_{res}$	Reverse transfer capacitance		-	88	-	nF
$Q_g$	Total gate charge	$V_{CC} = 520\text{ V}, I_C = 50\text{ A}, V_{GE} = 0\text{ to }15\text{ V}$ (see Figure 29. Gate charge test circuit)	-	150	-	nC
$Q_{ge}$	Gate-emitter charge		-	32	-	nC
$Q_{gc}$	Gate-collector charge		-	62	-	nC

**Table 5. IGBT switching characteristics (inductive load)**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400\text{ V}$ , $I_C = 50\text{ A}$ , $V_{GE} = 15\text{ V}$ , $R_G = 6.8\ \Omega$ (see Figure 28. Test circuit for inductive load switching)		42	-	ns
$t_r$	Current rise time			21	-	ns
$(di/dt)_{on}$	Turn-on current slope			1942	-	A/ $\mu$ s
$t_{d(off)}$	Turn-off delay time			130	-	ns
$t_f$	Current fall time			104	-	ns
$E_{on}^{(1)}$	Turn-on switching energy			0.88	-	mJ
$E_{off}^{(2)}$	Turn-off switching energy			1.57	-	mJ
$E_{ts}$	Total switching energy			2.45	-	mJ
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400\text{ V}$ , $I_C = 50\text{ A}$ , $V_{GE} = 15\text{ V}$ , $R_G = 6.8\ \Omega$ , $T_J = 175\text{ }^\circ\text{C}$ (see Figure 28. Test circuit for inductive load switching)		42	-	ns
$t_r$	Current rise time			24	-	ns
$(di/dt)_{on}$	Turn-on current slope			1700	-	A/ $\mu$ s
$t_{d(off)}$	Turn-off delay time			131	-	ns
$t_f$	Current fall time			184	-	ns
$E_{on}^{(1)}$	Turn-on switching energy			1.97	-	mJ
$E_{off}^{(2)}$	Turn-off switching energy			2.22	-	mJ
$E_{ts}$	Total switching energy			4.19	-	mJ
$t_{sc}$	Short-circuit withstand time	$V_{CC} \leq 400\text{ V}$ , $V_{GE} = 13\text{ V}$ , $T_{Jstart} \leq 150\text{ }^\circ\text{C}$	10		-	$\mu$ s
		$V_{CC} \leq 400\text{ V}$ , $V_{GE} = 15\text{ V}$ , $T_{Jstart} \leq 150\text{ }^\circ\text{C}$	6		-	

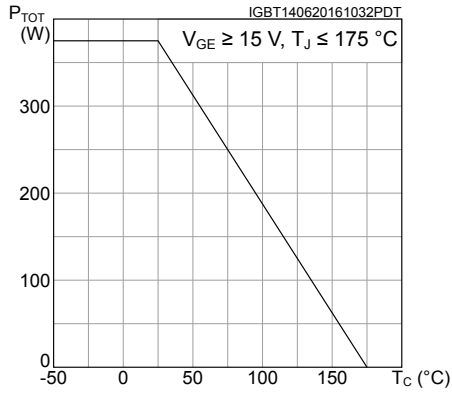
1. Including the reverse recovery of the diode.
2. Including the tail of the collector current.

**Table 6. Diode switching characteristics (inductive load)**

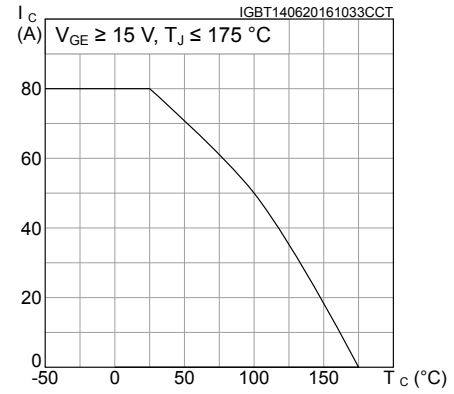
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit	
$t_{rr}$	Reverse recovery time	$I_F = 50\text{ A}$ , $V_R = 400\text{ V}$ , $V_{GE} = 15\text{ V}$ , $di/dt = 1000\text{ A}/\mu\text{s}$ (see Figure 28. Test circuit for inductive load switching)	-	162	-	ns	
$Q_{rr}$	Reverse recovery charge			-	1.37	-	$\mu$ C
$I_{rrm}$	Reverse recovery current			-	19	-	A
$dI_{rr}/dt$	Peak rate of fall of reverse recovery current during $t_b$			-	420	-	A/ $\mu$ s
$E_{rr}$	Reverse recovery energy			-	192	-	$\mu$ J
$t_{rr}$	Reverse recovery time		$I_F = 50\text{ A}$ , $V_R = 400\text{ V}$ , $V_{GE} = 15\text{ V}$ , $di/dt = 1000\text{ A}/\mu\text{s}$ , $T_J = 175\text{ }^\circ\text{C}$ (see Figure 28. Test circuit for inductive load switching)	-	262	-	ns
$Q_{rr}$	Reverse recovery charge			-	5.1	-	$\mu$ C
$I_{rrm}$	Reverse recovery current			-	34	-	A
$dI_{rr}/dt$	Peak rate of fall of reverse recovery current during $t_b$			-	160	-	A/ $\mu$ s
$E_{rr}$	Reverse recovery energy			-	676	-	$\mu$ J

## 2.1 Electrical characteristics (curves)

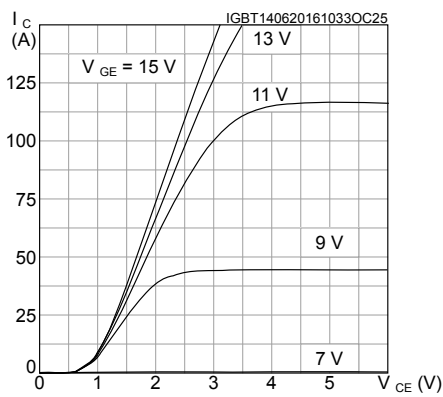
**Figure 1. Power dissipation vs. case temperature**



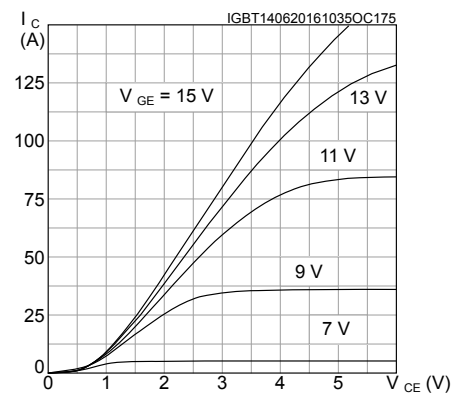
**Figure 2. Collector current vs. case temperature**



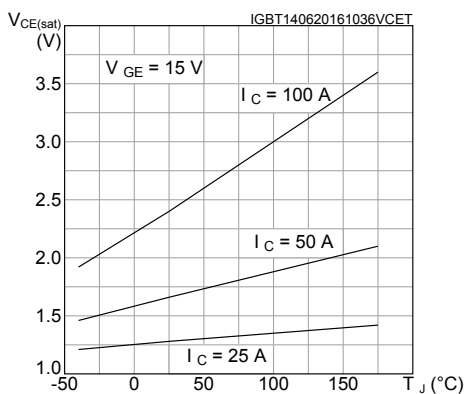
**Figure 3. Output characteristics (T<sub>J</sub> = 25 °C)**



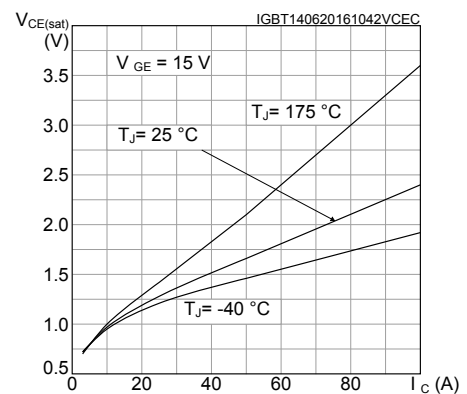
**Figure 4. Output characteristics (T<sub>J</sub> = 175 °C)**



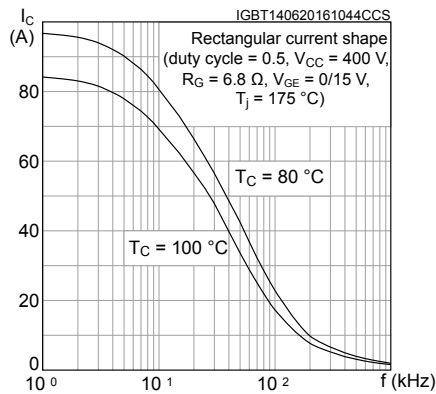
**Figure 5. V<sub>CE(sat)</sub> vs. junction temperature**



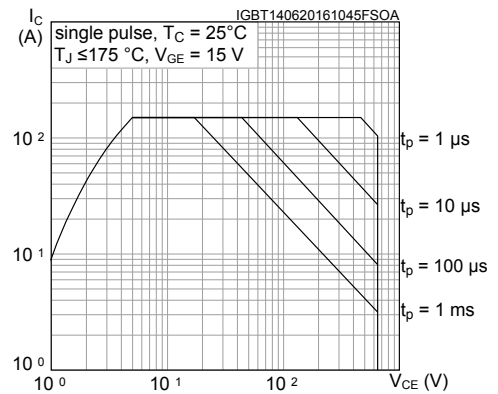
**Figure 6. V<sub>CE(sat)</sub> vs. collector current**



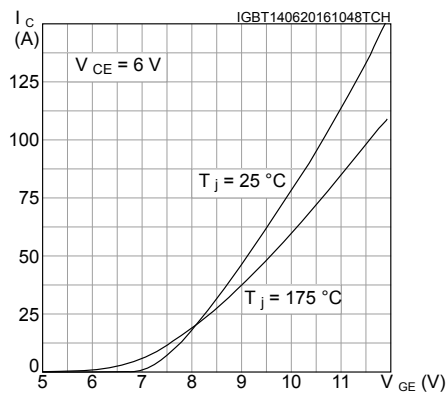
**Figure 7. Collector current vs. switching frequency**



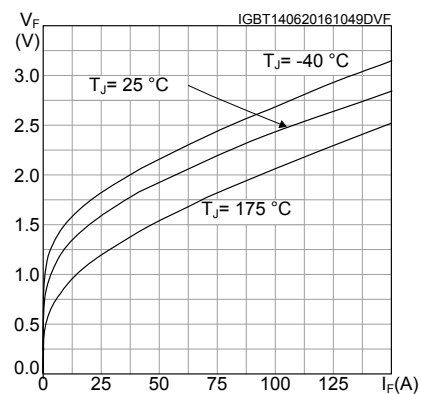
**Figure 8. Forward bias safe operating area**



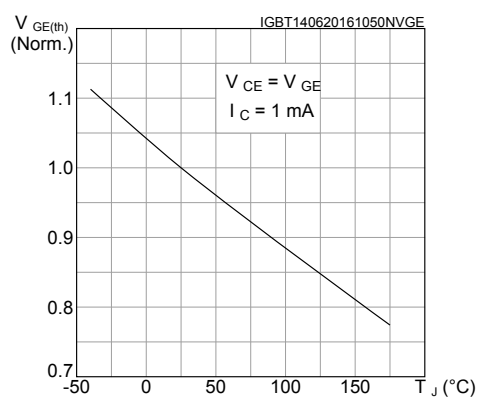
**Figure 9. Transfer characteristics**



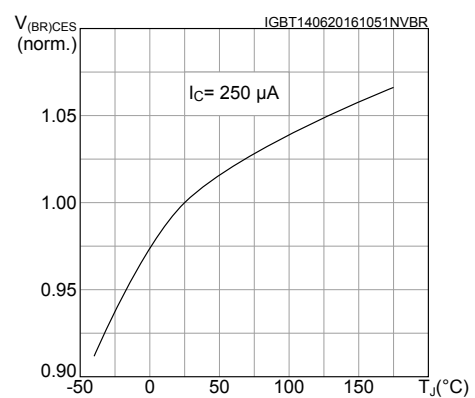
**Figure 10. Diode V\_F vs. forward current**



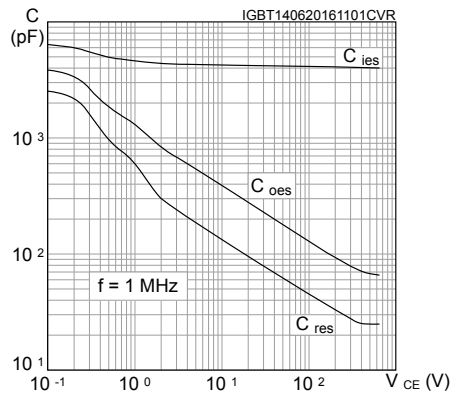
**Figure 11. Normalized V\_GE(th) vs. junction temperature**



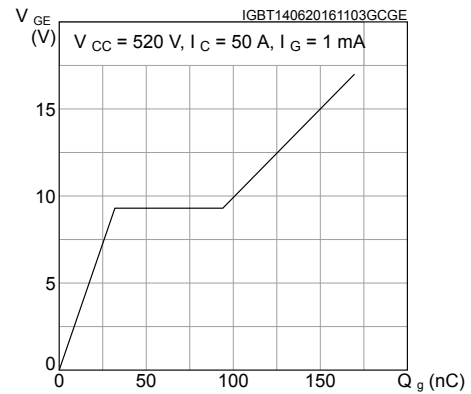
**Figure 12. Normalized V\_BR(CES) vs. junction temperature**



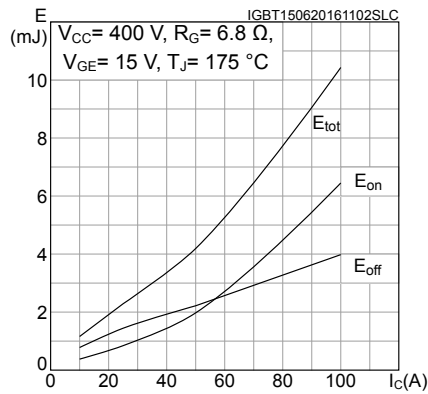
**Figure 13. Capacitance variations**



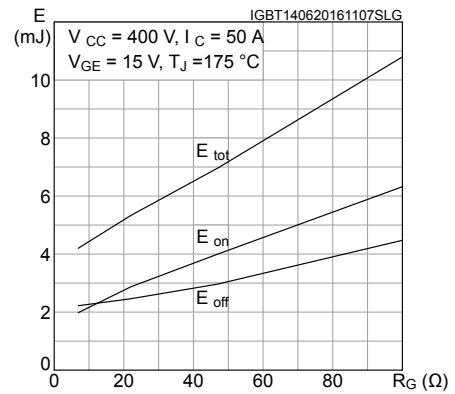
**Figure 14. Gate charge vs. gate-emitter voltage**



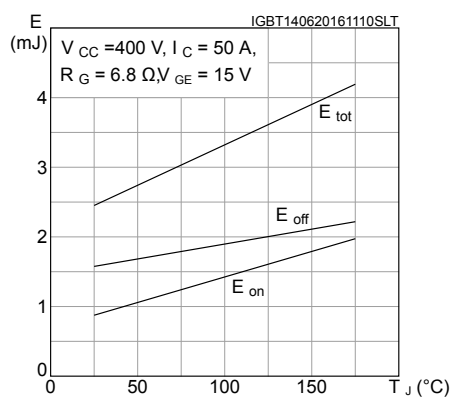
**Figure 15. Switching energy vs. collector current**



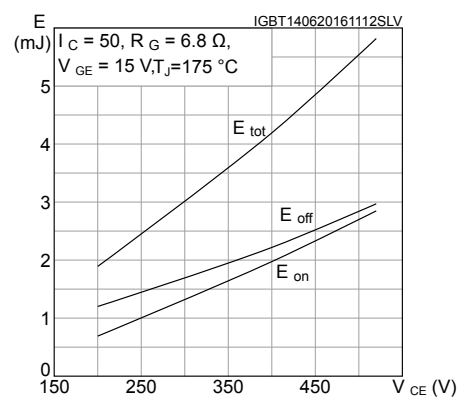
**Figure 16. Switching energy vs. gate resistance**



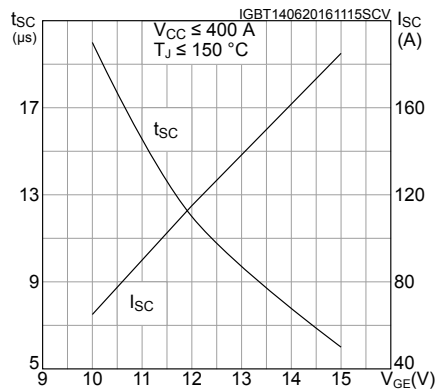
**Figure 17. Switching energy vs. temperature**



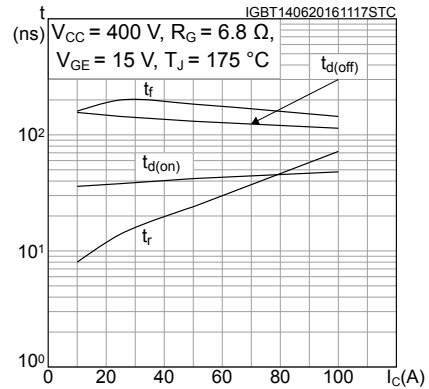
**Figure 18. Switching energy vs. collector emitter voltage**



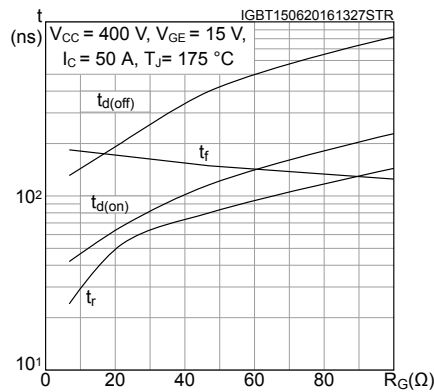
**Figure 19. Short-circuit time and current vs.  $V_{GE}$**



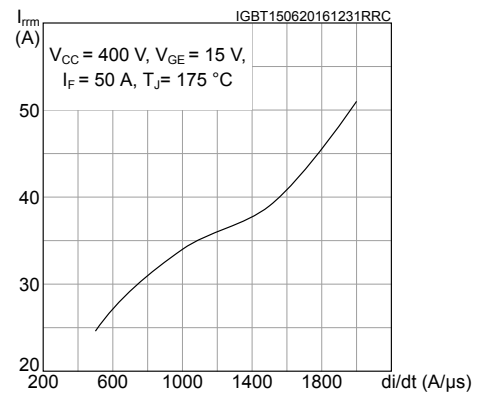
**Figure 20. Switching times vs. collector current**



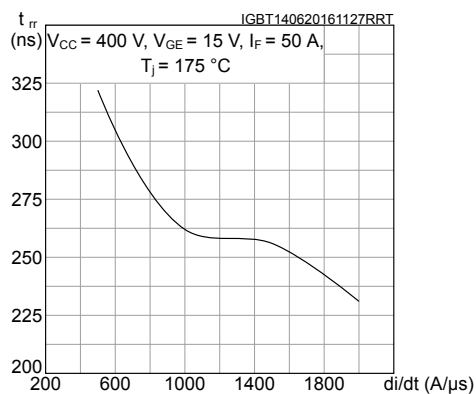
**Figure 21. Switching times vs. gate resistance**



**Figure 22. Reverse recovery current vs. diode current slope**



**Figure 23. Reverse recovery time vs. diode current slope**



**Figure 24. Reverse recovery charge vs. diode current slope**

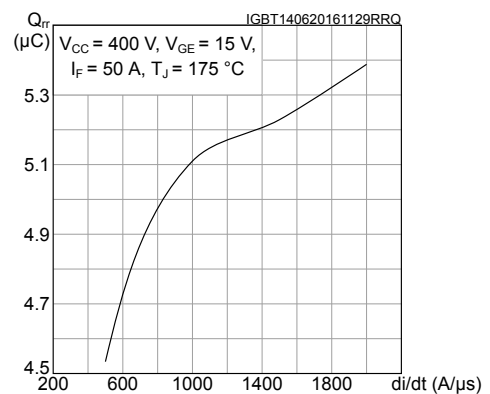




Figure 25. Reverse recovery energy vs. diode current slope

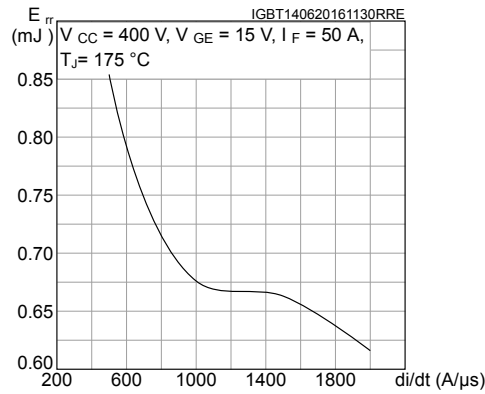


Figure 26. Thermal impedance for IGBT

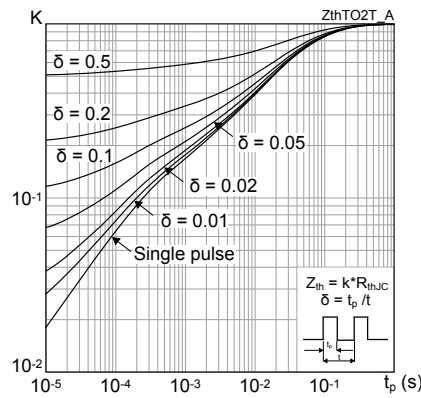
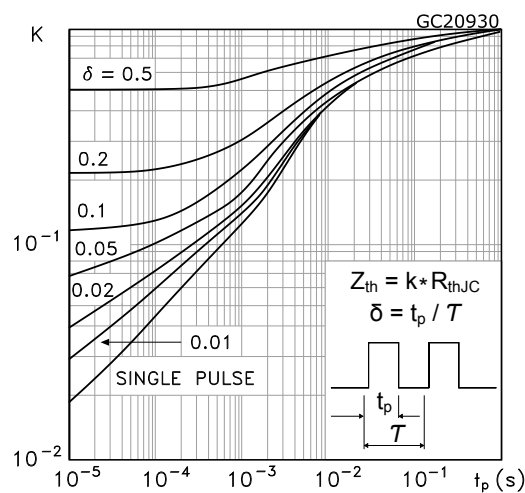


Figure 27. Thermal impedance for diode



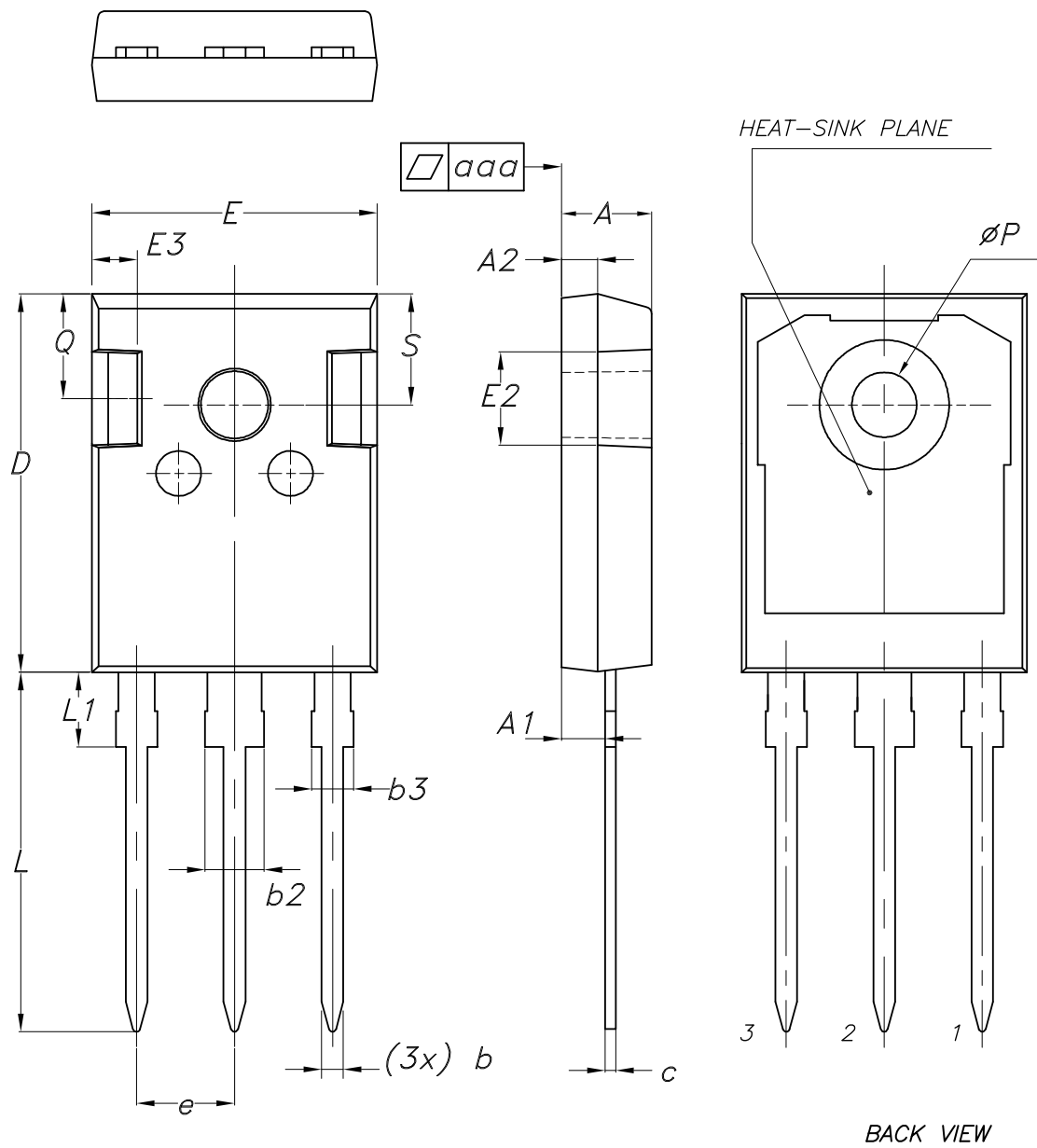


## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 TO-247 long leads package information

Figure 32. TO-247 long leads package outline



**Table 7. TO-247 long leads package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16		1.26
b2			3.25
b3			2.25
c	0.59		0.66
D	20.90	21.00	21.10
E	15.70	15.80	15.90
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	5.34	5.44	5.54
L	19.80	19.92	20.10
L1			4.30
P	3.50	3.60	3.70
Q	5.60		6.00
S	6.05	6.15	6.25
aaa		0.04	0.10

## Revision history

**Table 8. Document revision history**

Date	Revision	Changes
27-Nov-2015	1	First release.
14-Jun-2016	2	Modified: <i>features</i> and <i>applications</i> in cover page Modified: <i>Table 2: "Absolute maximum ratings", Table 4: "Static characteristics", Table 5: "Dynamic characteristics", Table 6: "IGBT switching characteristics (inductive load)", Table 7: "Diode switching characteristics (inductive load)"</i> Added: <i>Section 2.1: "Electrical characteristics (curves)"</i> Minor text changes
02-May-2017	3	Modified: <i>title, features</i> and <i>applications</i> on cover page. Modified <i>Table 4: "Static characteristics", Table 7: "Diode switching characteristics (inductive load)"</i> and <i>Figure 13: "Normalized <math>V_{(BR)CES}</math> vs. junction temperature"</i> . Updated <i>Section 4: "Package mechanical data"</i> . Minor text changes.
31-Mar-2023	4	Updated <a href="#">Table 3. Static characteristics</a> . Updated <a href="#">Section 4.1 TO-247 long leads package information</a> Minor text changes.

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<b>2</b>	<b>Electrical characteristics</b> .....	<b>3</b>
<b>2.1</b>	<b>Electrical characteristics (curves)</b> .....	<b>5</b>
<b>3</b>	<b>Test circuits</b> .....	<b>10</b>
<b>4</b>	<b>Package information</b> .....	<b>11</b>
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	<b>Revision history</b> .....	<b>13</b>

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